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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/824,549	04/02/2001	Yoshimitsu Nakashima	70840-55652	9425
21874 75	10/01/2004		EXAMINER	
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BOSTON, MA	02205		ART UNIT	PAPER NUMBER
			2873	
			DATE MAILED: 10/01/200	4

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)	
	Office Action Commence	09/824,549	NAKASHIMA, YOSHIMITSU	
	Office Action Summary	Examiner	Art Unit	
=		Alicia M Harrington	2873	
Period f	The MAILING DATE of this communication or Reply	n appears on the cover sheet w	th the correspondence address	
THE - External control	MAILING DATE OF THIS COMMUNICATION OF THIS COMMUNICATION OF THIS COMMUNICATION OF THIS COMMUNICATION OF THE PROPERTY OF THE PR	ON. FR 1.136(a). In no event, however, may a on. a reply within the statutory minimum of thineriod will apply and will expire SIX (6) MOI statute, cause the application to become A	reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).	
Status				
1)🛛	Responsive to communication(s) filed on	<u>01 July 1404</u> .		
2a)⊠	This action is FINAL . 2b)□	This action is non-final.		
3)	Since this application is in condition for all closed in accordance with the practice und	•		
Disposit	ion of Claims			
5)⊠ 6)⊠ 7)□	Claim(s) <u>1-20</u> is/are pending in the applicated 4a) Of the above claim(s) is/are with Claim(s) <u>5,6,11 and 14-20</u> is/are allowed. Claim(s) <u>1-4,8-10,12 and 13</u> is/are rejected Claim(s) is/are objected to. Claim(s) are subject to restriction and the control of the control o	hdrawn from consideration. d.		
Applicat	ion Papers			
10)⊠	The specification is objected to by the Examine The drawing(s) filed on <u>08 October 2002</u> is Applicant may not request that any objection to Replacement drawing sheet(s) including the countries of the oath or declaration is objected to by the	s/are: a) accepted or b) control of the drawing (s) be held in abeya correction is required if the drawing	nce. See 37 CFR 1.85(a). (s) is objected to. See 37 CFR 1.121(d).	
Priority (under 35 U.S.C. § 119			
12)⊠ a)	Acknowledgment is made of a claim for for All b) Some * c) None of: 1. Certified copies of the priority docur 2. Certified copies of the priority docur 3. Copies of the certified copies of the application from the International Buse the attached detailed Office action for a	ments have been received. ments have been received in A priority documents have beer ureau (PCT Rule 17.2(a)).	application No received in this National Stage	
Attachmen	• •	,		
	ce of References Cited (PTO-892)		Summary (PTO-413) s)/Mail Date	
3) 🔲 Infor	ce of Draftsperson's Patent Drawing Review (PTO-946 mation Disclosure Statement(s) (PTO-1449 or PTO/Ser No(s)/Mail Date		nformal Patent Application (PTO-152)	

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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-4, 8-10, 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over applicants admitted prior art (figure 5A-5B pages 2-7) in view of Lin et al US 6, 396,089).

Regarding claims 1,3,4,9,10 applicant's admitted prior art discloses a solid state imaging device comprising a semiconductor (11), light shield (14); a light reception section (12); single continuous (there is only one section) passivation section (15) with a refractive index (2.0; see page 6) and overlying the light shield section, light reception sections and aperture; a planarization section (16) overlying the passivation section, where the planarization section has a refractive index (1.5 ort 1.6; see page 6) smaller than the refractive index of the passivation section. However, applicant admitted prior art fails to discloses a planar /flat top surface for the passivation section. Although, it is well known in the art, as taught by Lin.

In the same field of endeavor, Lin discloses the planarization of semiconductor device where the passivation layer with SOG film that (304,306,308,310) is planarized (again there is only one multi-section; col. 3, lines 22-65). The passivation films have several layers that are placed over light reception area. Thus, it would have been obvious to one of ordinary skill in the

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art at the time the invention was made to modify, applicant's admitted prior art, as taught by Lin, to provide superior insulating property.

Regarding claim 2, applicant discloses the passivation film is made of silicon nitride based film (see pages 2-4).

Regarding claim 8, applicant's admitted prior art discloses a solid state imaging device comprising a semiconductor (11), light shield (14); a light reception section (12); single continuous passivation (there is only one section) section (15) film (n=2) overlying the light shield section, light reception sections and aperture; a planarization section (16) overlying the passivation section, where the planarization section has a refractive index (n=1.5 or 1.6; see page 6) smaller than the refractive index of the passivation section. However, applicant admitted prior art fails to discloses a planar /flat top surface for the passivation section, chemical machine polishing and insulation section. Although, it is well known in the art, as taught by Lin.

In the same field of endeavor, Lin discloses a method for manufacturing a semiconductor image sensor where the passivation film is planarized and where in the method comprises applying an SOG film and a forming another film over the SOG for forming the passivation section (again there is only one multi-section; col. 3, lines 22-65) to produce a substantial planarized surface. Thus, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify applicant's admitted prior art, as taught by Lin, since it would provide a planarized passivation layer which contributes to protection of the circuit and performance.

Regarding claim 13, applicant's admitted prior art discloses a solid state imaging device comprising a semiconductor (11), light shield (14); a light reception section (12); single

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continuous (there is only section) passivation section (15) film overlying the light shield section, light reception sections and aperture where the passivation provides moisture and chemical resistance (see page 3). However, applicant admitted prior art fails to discloses a planar /flat top surface. Although, it is well known in the art, as taught by Lin.

In the same field of endeavor, Lin discloses the planarization of semiconductor device where the passivation layer with SOG film that (304,306,308,310) is planarized (again there is only one multi-section; col. 3, lines 22-65) Thus, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify, applicant's admitted prior art, as taught by Lin et al. to provide a planar surface which enhances image quality and provides protection for the detector.

3. Claims 7,12 are rejected under 35 U.S.C. 103(a) as being unpatentable over applicants admitted prior art (figure 5A-5B pages 2-7) in view of Lin et al US 6, 396,089), further in view of De Santi et al (EP 0887 847 A1).

Regarding claims 7 and 12, applicant's admitted prior art discloses a solid state imaging device comprising a semiconductor (11), light shield (14); a light reception section (12); passivation section (15) film overlying the light shield section, light reception sections and aperture where the passivation provides moisture and chemical resistance (see page 3); a planarization section (16;n=2) overlying the passivation section, where the planarization section has a refractive index (n=1.5 ort 1.6; see page 6) smaller than the refractive index of the passivation section. However, applicant admitted prior art fails to disclose a planar /flat top

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surface for the passivation section, an insulation layer and chemical machine polishing as claimed. Although, it is well known in the art, as taught by Lin.

In the same field of endeavor, Lin discloses the planarization of semiconductor device where the passivation layer with SOG film that (304,306,308,310) is planarized (again there is only one multi-section; col. 3, lines 22-65). The passivation films have several layers that are placed over light reception area. Thus, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify, applicant's admitted prior art, as taught by Lin, to provide superior insulating property.

In addition, the application and Lin discloses applying the thin film forming the passivation section by using a CVD technique or the like. Although, applicant and Lin fail to produce a planarized layer using chemical mechanical polishing, it would have been obvious to one of ordinary skill in the art at the time the invention was made to modify applicant and park, to include this process since it is a notoriously well known semiconductor planarization layering process, as taught by De Santi (EP 0887,847) in col. 3,lines 35-36.

Response to Arguments

4. Applicant's arguments filed on 7/14/04 have been fully considered but they are not persuasive. Applicant argues that Lin teaches a discontinuous, two-part section. However, the Examiner doesn't agree, I contend that Lin teaches a planar passivation section. The detector does not have two passivation sections. Thus the rejections of claims 1-4,7-10,12, and 13 will be repeated.

Allowable Subject Matter

5. Claim 5,6, 11,14-20 is allowed.

The following is a statement of reasons for the indication of allowable subject matter:

Regarding claims 5 and 14, prior art taken either singularly or in combination fails to anticipate or fairly suggest the limitations of the dependent claims, in such manner that a rejection under 35 U.S.C 102 or 103 would be proper. The prior art fails to teach a combination of all the claimed features as presented in independent claims, which at least include forming a single, continuous thin film used for forming the passivation section on the light shielding section and the aperture; and flattening a surface of the single continuous thin film to form the passivation section by chemical machine polishing as claimed.

Regarding claim 6, prior art taken either singularly or in combination fails to anticipate or fairly suggest the limitations of the dependent claims, in such manner that a rejection under 35 U.S.C 102 or 103 would be proper. The prior art fails to teach a combination of all the claimed features as presented in independent claims, which include a method for producing a solid state imaging device where flattening of the passivation section is performed under the condition that a selective ration of 1:1 implemented as claimed.

Regarding claim 15, prior art taken either singularly or in combination fails to anticipate or fairly suggest the limitations of the dependent claims, in such manner that a rejection under 35 U.S.C 102 or 103 would be proper. The prior art fails to teach a combination of all the claimed features as presented in independent claims, which at least include a planarization section overlying the substantially flat top surface of said passivation section, wherein the planarization

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section has a refractive index smaller than the refractive index of the passivation section, wherein a selection ratio of the planarization section to the passivation section is about 1: 1 as claimed.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Alicia M Harrington whose telephone number is 571 272 2330. The examiner can normally be reached on Monday - Thursday 9:30-6:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Georgia Epps can be reached on 571 272 2328. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

All

AMH

Alicia M Harrington Examiner Art Unit 2873

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